



Material Content Data Sheet



Halogen-Free

Sales Product Name	IP1120N04S3-02	Issued	28. April 2021
MA#	MA000361816		
Package	PG-TO262-3-1	Weight*	1581.39 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.237	0.77	0.77	7738	7738
leadframe	inorganic material	phosphorus	7723-14-0	0.255	0.02		161	
	non noble metal	iron	7439-89-6	0.851	0.05		538	
	non noble metal	copper	7440-50-8	849.682	53.75	53.82	537303	538002
wire	non noble metal	aluminium	7429-90-5	13.976	0.88	0.88	8838	8838
encapsulation	inorganic material	zinc oxide	1314-13-2	5.750	0.36		3636	
	miscellaneous	miscellaneous	-	22.999	1.45		14543	
	plastics	epoxy resin	-	86.246	5.45		54538	
	inorganic material	silicon dioxide	60676-86-0	459.976	29.09	36.35	290869	363586
lead finish	non noble metal	tin	7440-31-5	15.198	0.96	0.96	9610	9610
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	144	145
solder	non noble metal	tin	7440-31-5	0.153	0.01		97	
	noble metal	silver	7440-22-4	0.191	0.01		121	
	non noble metal	lead	7439-92-1	7.296	0.46	0.48	4613	4831
heatspreader	inorganic material	phosphorus	7723-14-0	0.032			20	
	non noble metal	iron	7439-89-6	0.106	0.01		67	
	non noble metal	copper	7440-50-8	106.210	6.72	6.73	67163	67250
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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